

Electronic Patent Application Fee Transmittal

| Application Number: | 10581851 | | | |
|---|--------------------------------------|----------|--------|----------------------|
| Filing Date: | 22-Feb-2007 | | | |
| Title of Invention: | Bonding Apparatus and Bonding Method | | | |
| First Named Inventor/Applicant Name: | Hachiya Takeuchi | | | |
| Filer: | Joseph W. Price/Sharon Farnus | | | |
| Attorney Docket Number: | 42598-4100 | | | |
| Filed as Large Entity | | | | |
| U.S. National Stage under 35 USC 371 Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Independent claims in excess of 3 | 1614 | 1 | 220 | 220 |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
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| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 220 |